

11-24-2004

Attorney Docket No. 14963-47526

102888509

To the Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Chin-Long KU
Chin-Wen YEH

2. Name and address of receiving party(ies):

HON HAI Precision Industry CO., LTD.
66, Chung Shan Road
Tu-cheng City
Taipei Hsien, Taiwan, R.O.C.Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ NoAdditional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:

Execution Date: November 10, 2004

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: November 10, 2004

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Tim Tingkang Xia, Esq.
Address: Morris, Manning & Martin, LLP
1600 Atlanta Financial Center
3343 Peachtree Street, N.E.
Atlanta, Georgia 30326

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Enclosed
☐ Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to our Deposit account number:

DO NOT USE THIS SPACE

9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Tim Tingkang Xia

Name of Person Signing

Signature

November 16, 2004

Date

Total number of pages including cover sheet, attachments, and document: 2

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
Director - U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of information systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

11/23/2004 ECDOPER 00000264 10989762

01 FC:8021

40.00 OP

PATENT
REEL: 016003 FRAME: 0728

ASSIGNMENT

WHEREAS, We, Chin-Long Ku, residing at Tu-Cheng, Taiwan; Chin-Wen Yeh, residing at Tu-Cheng, Taiwan; have made certain new and useful inventions and improvements for which we filed or shall file an application for Letters Patent of the United States on 11-16-2004, application Serial No. _____ which is entitled Heat Dissipation Device Assembly with Fan Cover. We also authorize counsel for Applicant(s) to enter above the serial number of the application or other related information when it becomes available.

AND WHEREAS, HON HAI Precision Industry CO., LTD, a corporation having an office and place of business at 66, Chung Shan Road, Tu-cheng City, Taipei Hsien, Taiwan, ROC (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW THEREFORE, to all whom it may concern, be it known that for and in consideration of the sum of One Dollar and other good and valuable considerations, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the

entire right, title and interest in and to the improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 10th day of
November, 2004.

Chin-Long Ku
Chin-Long Ku

IN TESTIMONY WHEREOF, I have hereunto set my hand this 10th day of
November, 2004.

Chin-Wen Yeh
Chin-Wen Yeh